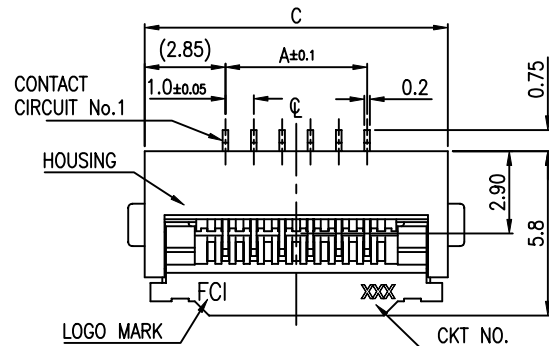
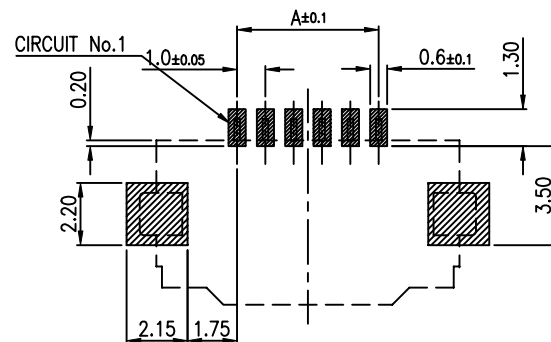
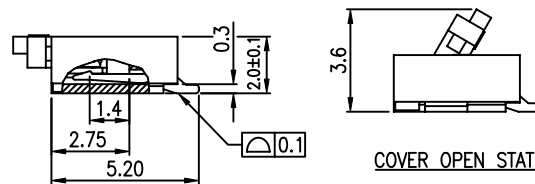


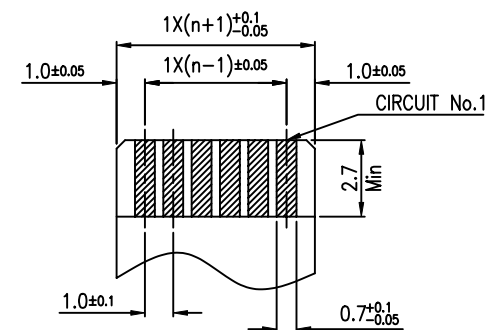
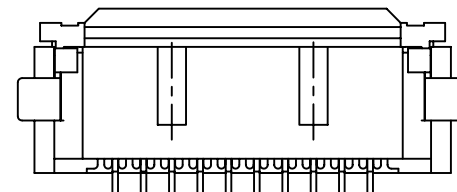
CKT	DIM.A	DIM.B	DIM.C
006	5.00	7.06	10.7
008	7.00	9.06	12.7
010	9.00	11.06	14.7
012	11.00	13.06	16.7



RECOMMENDED PC BOARD PATTERN DIM.(REF.)



COVER OPEN STATE



APPLICABLE FPC RECOMMENDED DIM.
(THICKNESS: 0.3±0.03)

NOTES:

- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0.
 - ACTUATOR: THERMOPLASTIC, HIGH TEMP., UL94V-0.
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
- FINISH:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - CONTACT AREA AND SOLDER TAIL: GOLD FLASH OVERALL
 - FITTING NAIL:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - MATTE TIN PLATING 100u" MIN. OVERALL
- REFLOW SOLDER CAPABLE TO 260°C PEAK TEMP. FOR 10 SECONDS MAX.
- SPEC. PLS. REFER TO GS-12-579.
- PACKAGE PLS. REFER TO GS-14-1331.
- PART NUMBER DESCRIPTION:

10089709-XXX 0 1 0 LF
 NO OF CONTACTS(CKT) ——— X ——— LEAD FREE
 PACKING ——— 0: TAPE & REEL ——— COLOR
 ——— X: HOUSING ACTUATOR
 ——— 0: NATURAL BLACK
 PLATING
 1: GOLD FLASH OVERALL

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com		
ltr	ecn no	dr	date	linear	.X ± 0.25				
A	T08-1182	WL	11/06/08	linear	.XX ± 0.15	projection	title 1.0mm FPC CONN. SMT R/A B/C TYPE		
B	T08-1196	WL	12/10/08	linear	.XXX ± 0.10	MM			
C	T09-1001	WL	01/05/09	angles	0° ± 2°	scale	product family FPC size dwg no A4 10089709		
D	T09-1005	WL	01/20/09	dr	LEIF SHEN 08-06-18	scale			
E	T09-1132	WL	10/15/09	enr	DENNIS GOH 08-10-20	scale	code SNG sheet 1 of 1		
F	T10-0046	WL	04/15/10	chr	DENNIS GOH 08-10-20	scale			
				appd	JOEY NG 08-10-20	scale	cage code 22526		
sheet index	revision sheet	F	1						